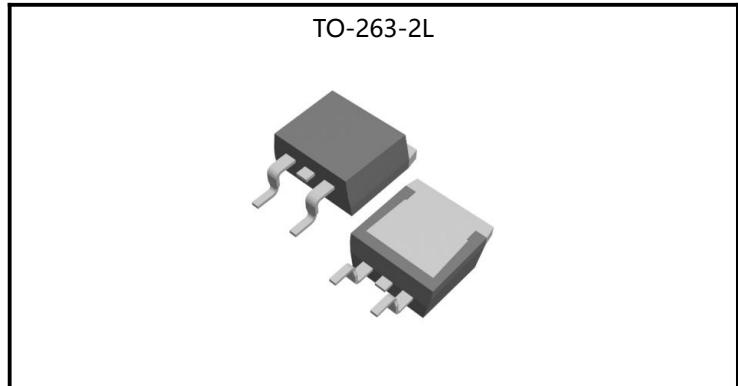


MOSFET

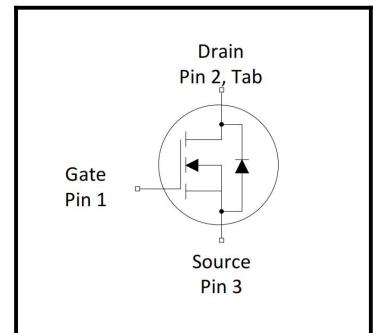
10 Amps, 500 Volts N-CHANNEL MOSFET

FEATURE

- ◆ Low gate charge
- ◆ Low Ciss
- ◆ Fast switching
- ◆ 100% avalanche tested
- ◆ Improved dv/dt capability
- ◆ RoHS 2.0 Compliant



Parameter	Values	Unit
Bvdss	500	V
Id	10	A
Rdson(max)	0.8	Ω



Ordering Code	Marking	Package	Packaging
10N50B	10N50B	TO-263-3L	Tape&Reel

Absolute Maximum Ratings($T_c=25^\circ\text{C}$,unless otherwise noted)

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Drain-Source Voltage	V_{DSS}	-	-	500	V	-
Gate-Source Voltage	V_{GS}	-30	-	30	V	-
Continuous Drain Current(Package Limited)	I_D	-	-	10	A	$T_c=25^\circ\text{C}$
		-	-	6	A	$T_c=100^\circ\text{C}$
Pulsed Drain Current(Note1)	I_{DM}	-	-	40	A	-
Single Pulse Avalanche Energy	E_{AS}	-	-	507	mJ	$L=10\text{mH}, V_D=50\text{V}, T_c=25^\circ\text{C}$
Maximum Power Dissipation	P_D	-	-	130	W	$T_c=25^\circ\text{C}$
Reverse Diode dV/dt (Note2)	dV/dt	-	-	5	V/ns	-
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55	-	150	°C	-
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T_L	-	-	260	°C	-

Thermal Characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Thermal resistance , Channel to Case	$R_{th(ch-c)}$	-	0.96	-	°C/W	-

Electrical Characteristics ($T_c=25^\circ\text{C}$,unless otherwise noted)

Static characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Drain-Source Breakdown Voltage	BV_{DSS}	500	-	-	V	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	-	-	1	μA	$V_{DS}=500\text{V}, V_{GS}=0\text{V}$
Gate-Body Leakage Current,Forward	I_{GSSF}	-	-	100	nA	$V_{GS}=30\text{V}, V_{DS}=0\text{V}$
Gate-Body Leakage Current,Reverse	I_{GSSR}	-	-	-100	nA	$V_{GS}=-30\text{V}, V_{DS}=0\text{V}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	2.0	-	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$
Drain-Source On-State Resistance	$R_{DS(on)}$	-	0.55	0.80	Ω	$V_{GS}=10\text{V}, I_D=4\text{A}$
Gate Resistance	R_g	-	1.7	-	Ω	$V_{GS}=0\text{V}, V_{DS} \text{ Open}, f=1\text{MHz}$
Forward Transconductance	g_{fs}	-	3.4	-	S	$V_{DS}=5\text{V}, I_D=4\text{A}$

Dynamic characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Input Capacitance	C _{iss}	-	1565	-	pF	V _{DS} =25V,V _{GS} =0V,f=1.0MHZ
Output Capacitance	C _{oss}	-	118	-	pF	V _{DS} =25V,V _{GS} =0V,f=1.0MHZ
Reverse Transfer Capacitance	C _{rss}	-	39	-	pF	V _{DS} =25V,V _{GS} =0V,f=1.0MHZ
Turn-On Delay Time	t _{d(on)}	-	16.8	-	ns	V _{DD} =250V,R _G =10Ω,V _{GS} =10V,R _L =66Ω
Turn-On Rise Time	t _r	-	1.6	-	ns	V _{DD} =250V,R _G =10Ω,V _{GS} =10V,R _L =66Ω
Turn-Off Delay Time	t _{d(off)}	-	164.4	-	ns	V _{DD} =250V,R _G =10Ω,V _{GS} =10V,R _L =66Ω
Turn-Off Fall Time	t _f	-	998.2	-	ns	V _{DD} =250V,R _G =10Ω,V _{GS} =10V,R _L =66Ω

Gate charge characteristics

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Total Gate Charge	Q _g	-	28.5	-	nC	V _{DS} =400V,I _D =8A,V _{GS} =10V
Gate-Source Charge	Q _{gs}	-	8.5	-	nC	V _{DS} =400V,I _D =8A,V _{GS} =10V
Gate-Drain Charge	Q _{gd}	-	6.7`	-	nC	V _{DS} =400V,I _D =8A,V _{GS} =10V

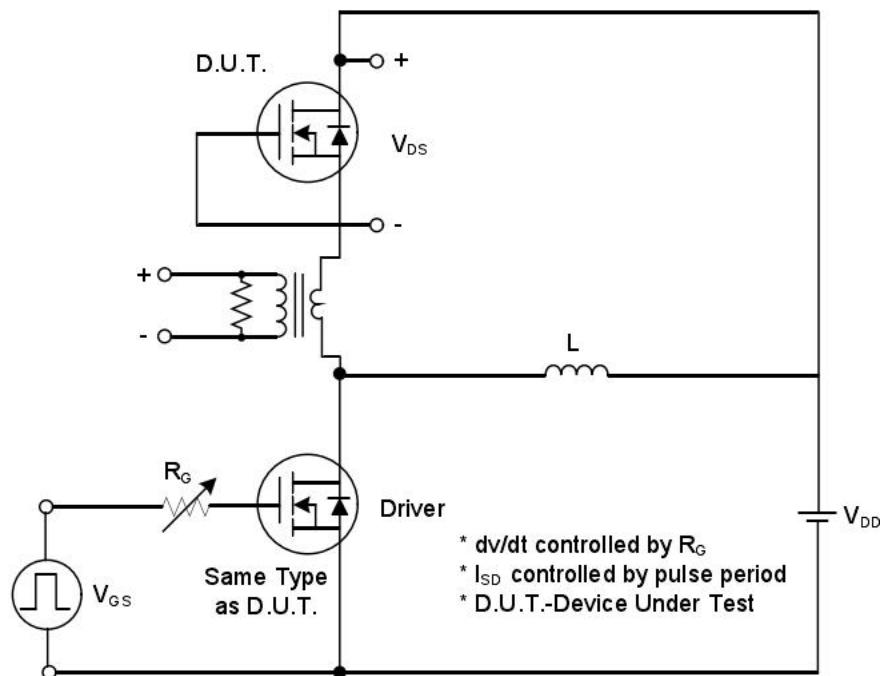
Reverse diode

Parameter	Symbol	Values			Unit	Note/Test Conditions
		Min	Typ	Max		
Continuous Diode Forward Current	I _S	-	-	10	A	-
Pulsed Diode Forward Current	I _{SM}	-	-	40	A	-
Diode Forward Voltage	V _{SD}	-	-	1.5	V	I _S =4A,V _{GS} =0V
Reverse Recovery Time	t _{rr}	-	172	-	ns	V _D =20V,I _F =1A
Reverse Recovery Charge	Q _{rr}	-	483.7	-	nC	di/dt=100A/μs,(Note2)

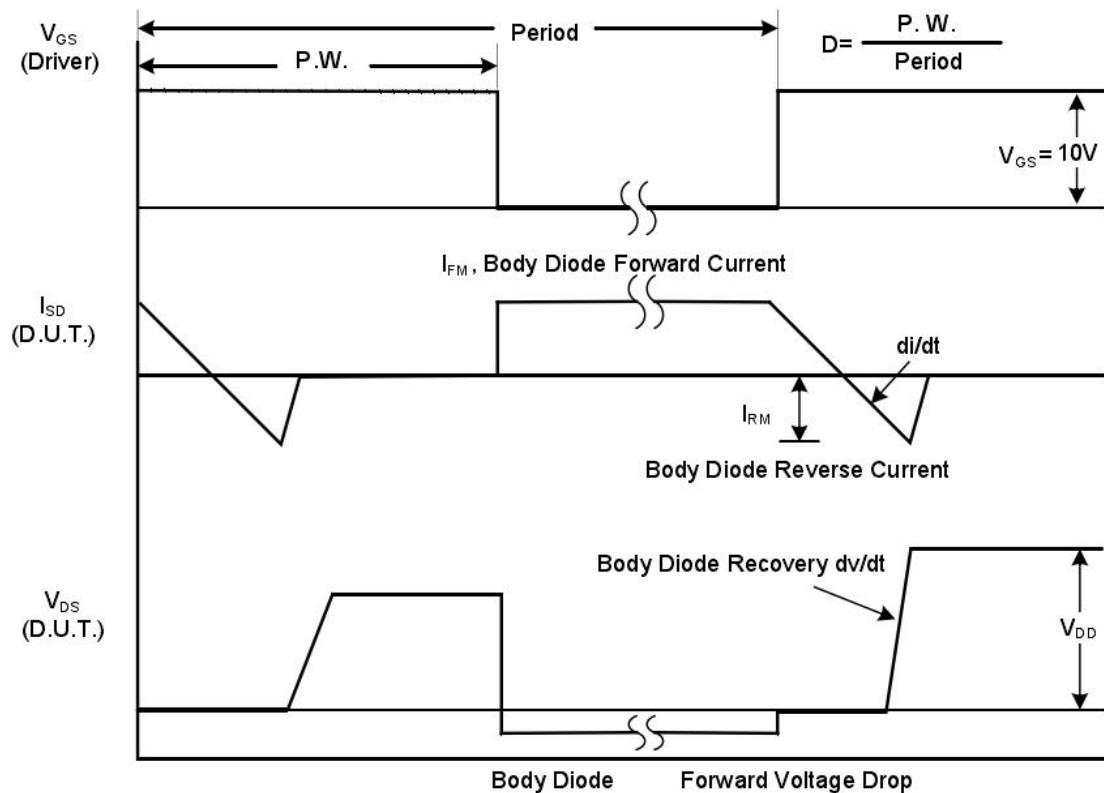
Notes

- Repetitive Rating:pulse width limited by maximum junction temperature.
- Pulse width≤300us,duty cycle≤2%.

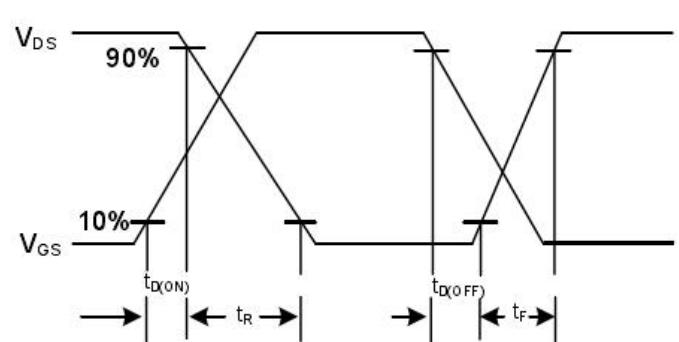
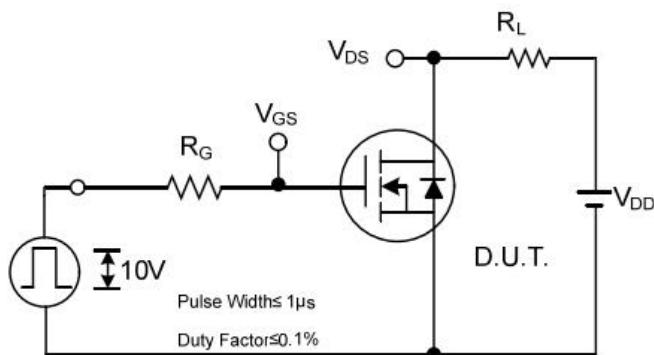
RATING AND CHARACTERISTIC CURVES



Peak Diode Recovery dv/dt Test Circuit

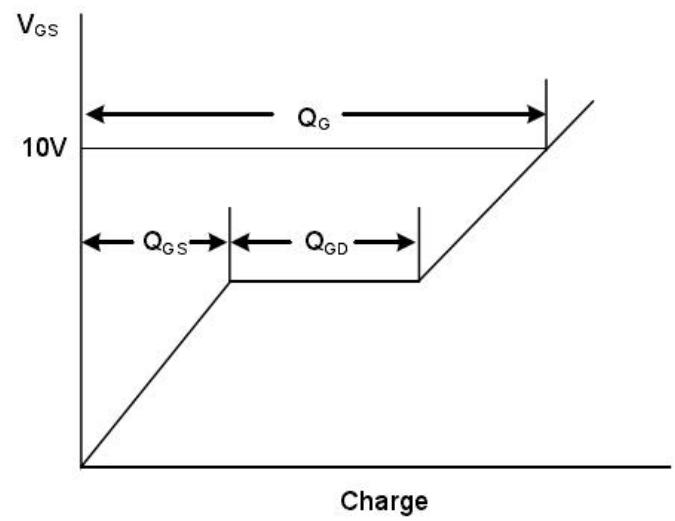
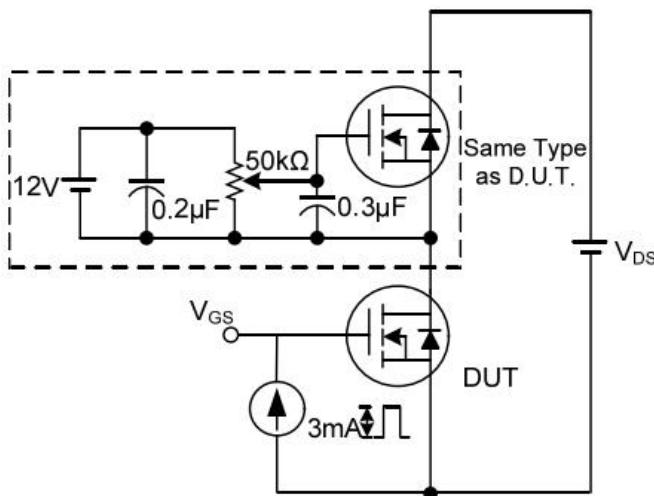


Peak Diode Recovery dv/dt Waveforms



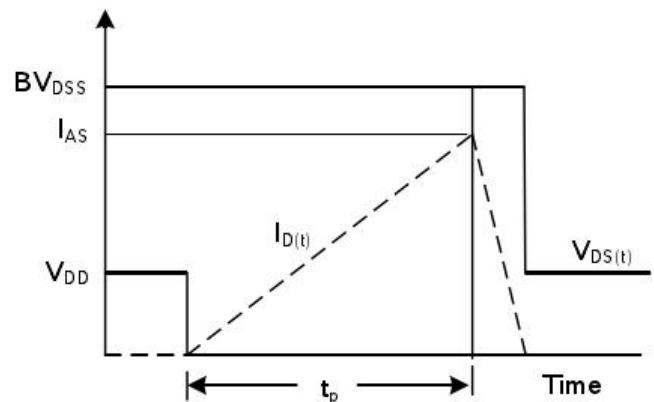
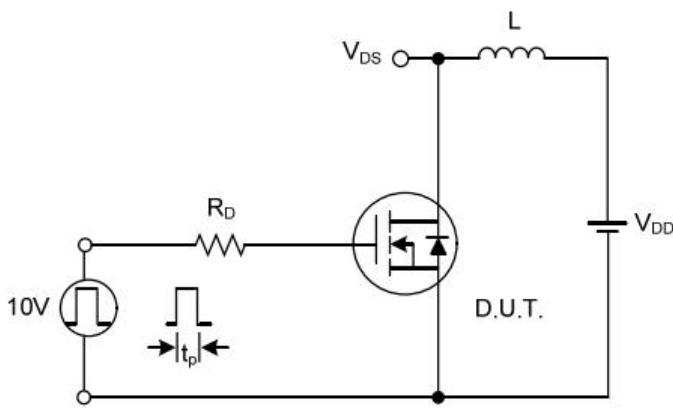
Switching Test Circuit

Switching Waveforms



Gate Charge Test Circuit

Gate Charge Waveform



Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

RATING AND CHARACTERISTIC CURVES

Figure.1 Typical Output Characteristics

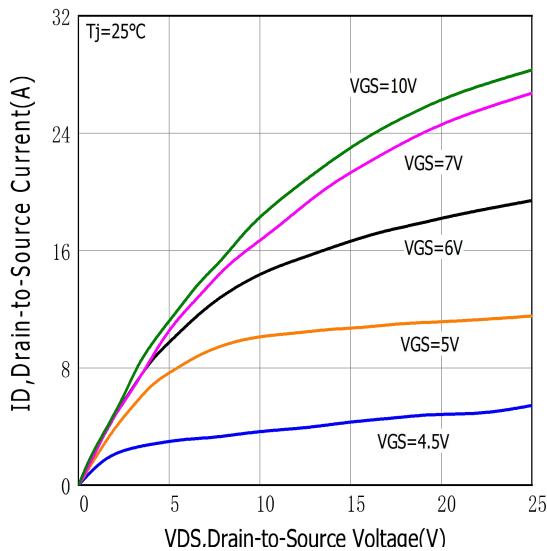


Figure.2 Typical Gate Charge vs Gate to Source Voltage

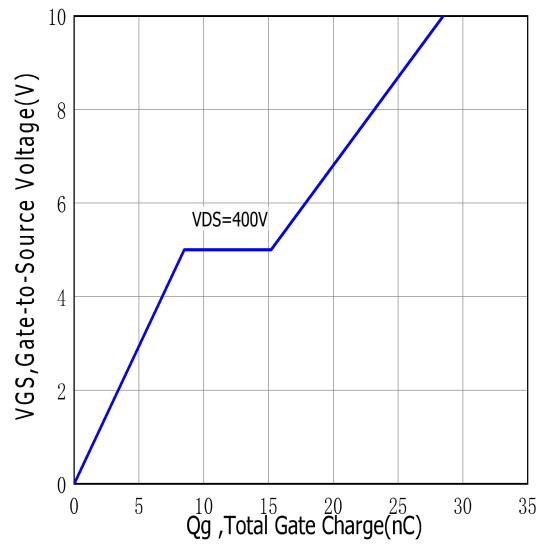


Figure.3 Typical Body Diode Transfer Characteristics

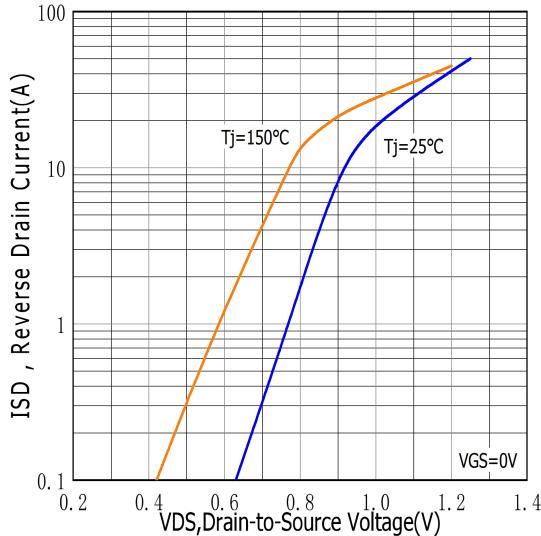


Figure.4 Typical Capacitance vs Drain to Source Voltage

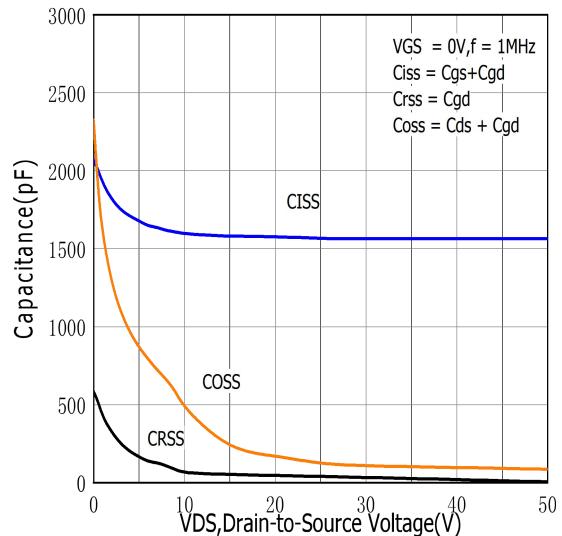


Figure.5 Typical Breakdown Voltage vs Junction Temperature

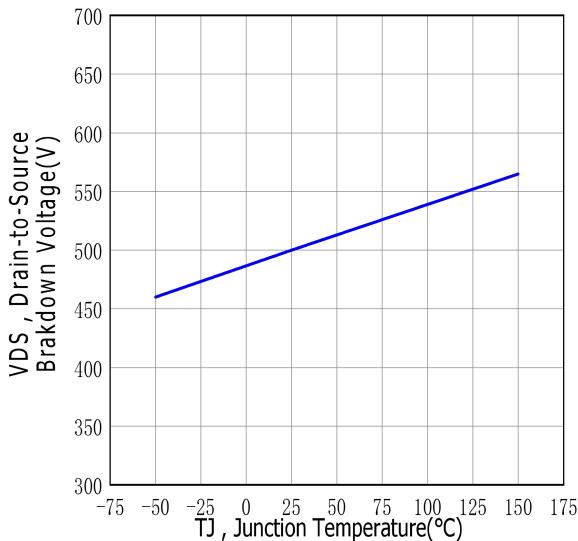


Figure.6 Typical Drain to Source on Resistance vs Junction Temperature

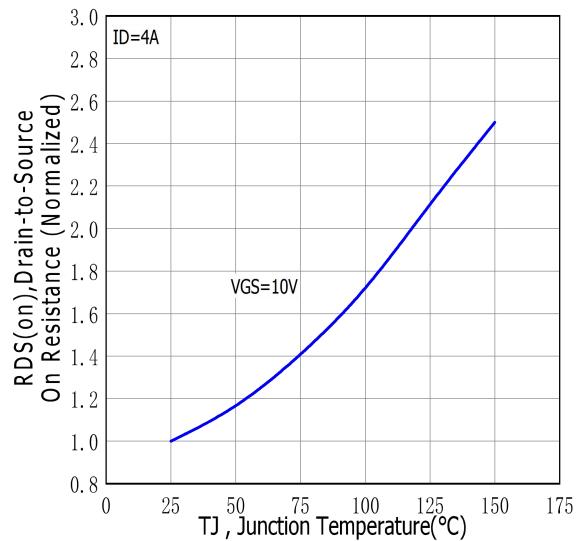


Figure.7 Maximum Forward Bias Safe Operating Area

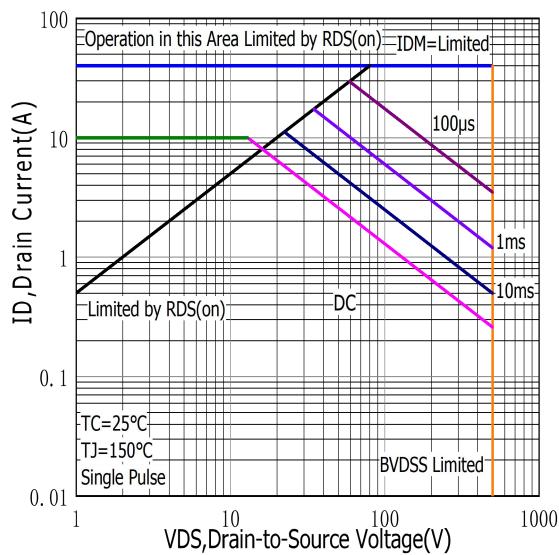


Figure.8 Typical Drain to Source ON Resistance vs Drain Current

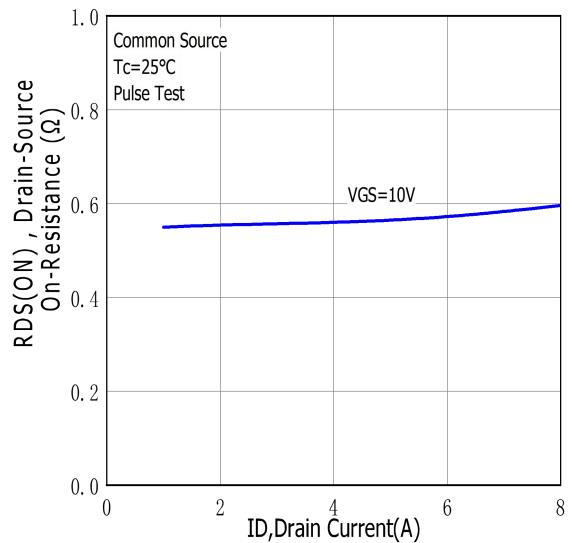


Figure.9 Maximum EAS vs Channel Temperature

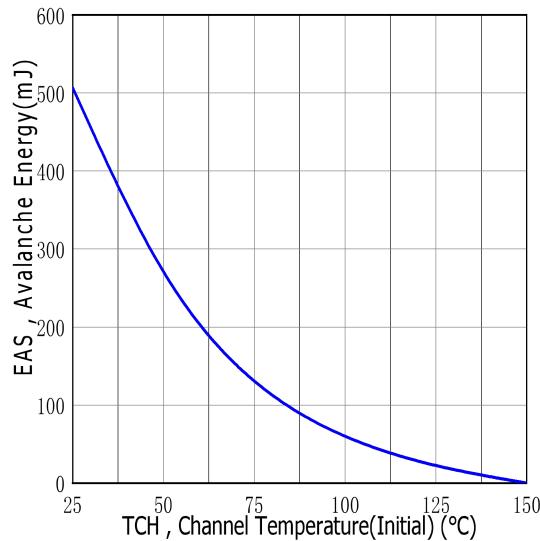


Figure.10 Typical Threshold Voltage vs Case Temperature

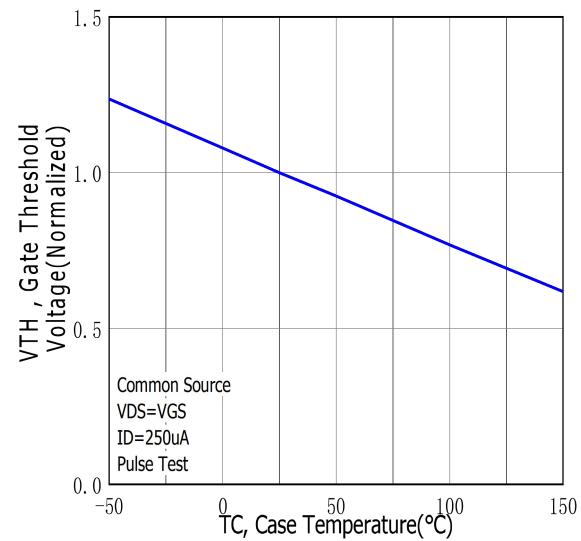


Figure.11 Typical Transfer Characteristics

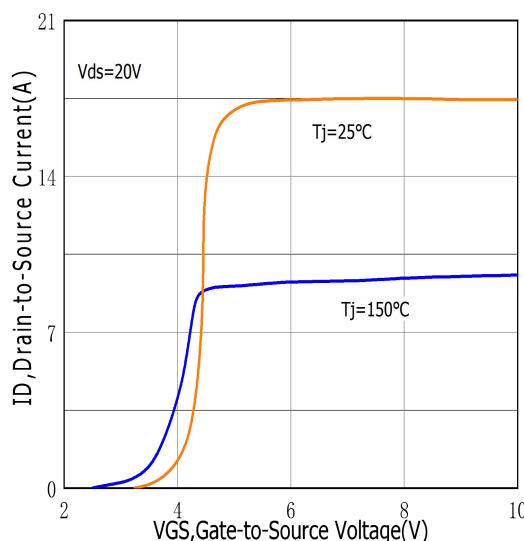


Figure.12 Maximum Power Dissipation vs Case Temperature

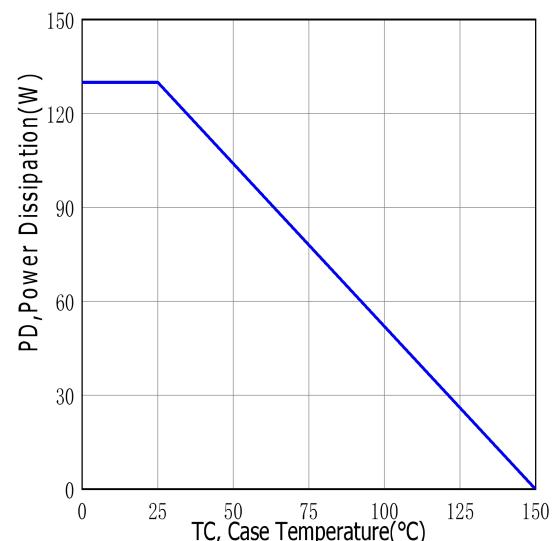
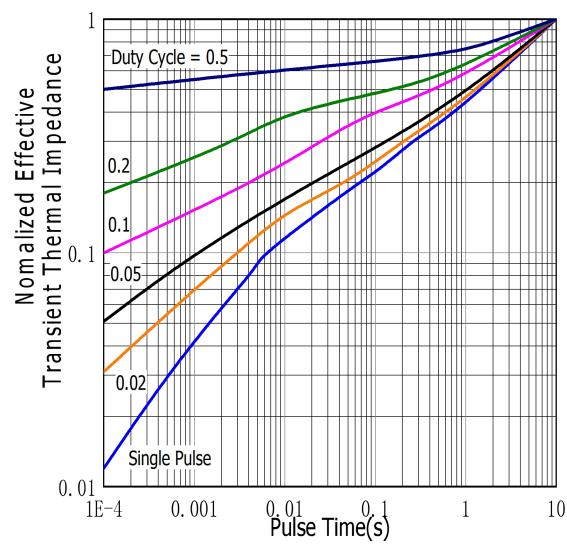
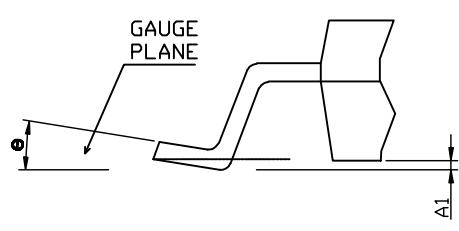
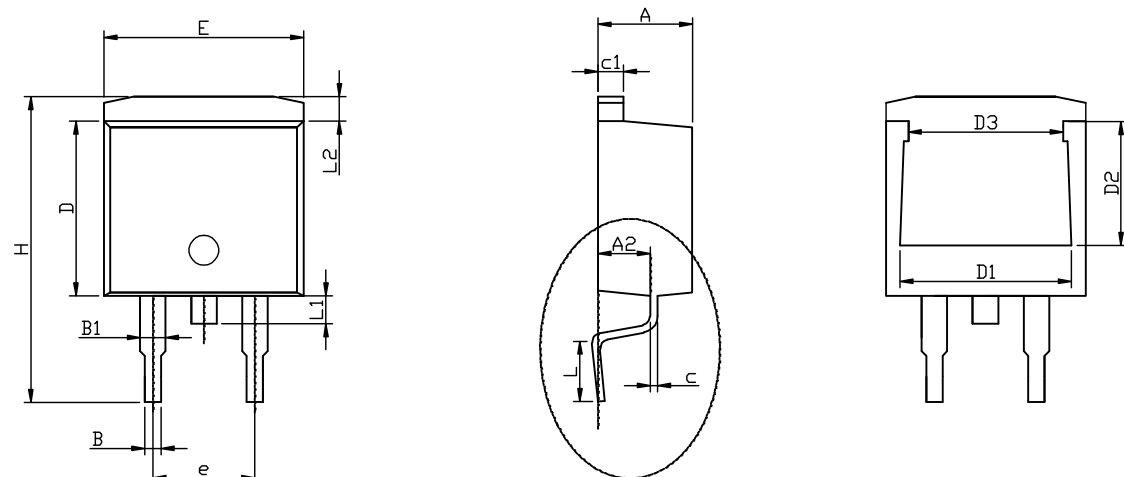


Figure.13 Maximum Effective Thermal Impedance , Junction to Case

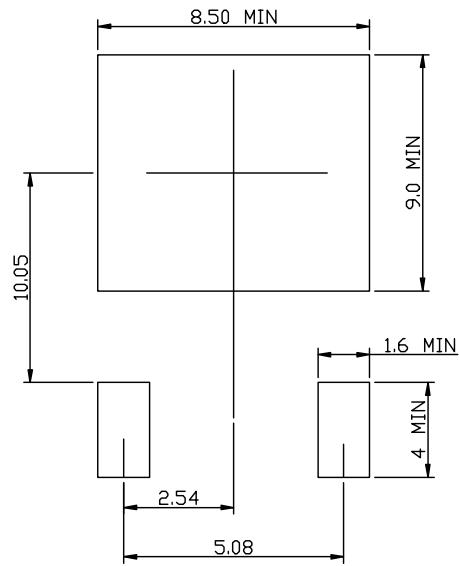


TO-263-2L PACKAGE OUTLINE



VIEW1

RECOMMENDED LAND PATTERN



UNIT: mm

	MIN	NOM	MAX
A	4.50	4.70	4.90
A1	0.05	0.15	0.30
A2	2.45	2.60	2.70
B	0.72	0.82	0.92
B1	1.12	1.27	1.42
c	0.28	0.38	0.48
c1	1.17	1.27	1.37
D	8.46	8.66	8.86
D1	7.90	8.10	8.40
D2	5.50	5.70	5.90
D3	7.10	7.30	7.50
E	9.85	10.15	10.45
e		5.08BCS	
H	14.75	15.15	15.55
L	2.30	2.55	2.80
L1	1.20	1.40	1.60
L2	1.01	1.23	1.50
Θ	0°	7°	8°